

Technical Data

HEAT SINK COMPOUND – NON SILICONE

Servisol Heat Sink Compound – Non-Silicone is recommend for use on electrical and electronic components that require improved thermal conductivity or the efficient dissipation of heat.

Heat Sink Compound – Non Silicone will not cause problems associated with the use of silicone, such as high contact resistance and soldering difficulties.

Heat Sink Compound – Non Silicone can be used on diodes, transistors, heat sinks, semi-conductors, thermostats, power resistors and radiators. It is presented in a handy to use syringe format, 2ml, 10ml and 35ml sizes cover a wide variety of applications. This syringe allows pin-point application and minimises wasteful over-application.

ADVANTAGES

Syringe Presentation	:	Pin point application and economy in use
Wide Operating Temperature	:	Suitable for many applications
Excellent Thermal Conductivity	:	Rapid Heat Dissipation

TECHNICAL DATA

Appearance	:	White Paste
Base Oil	:	Synthetic
Evaporation after 4 days at 100°C	:	1.4%
Temperature Range	:	-50°C to +130°C
Permitivity @ 1MHz	:	4.2
Specific Resistance	:	1 x 10 ¹⁴ ohms/cm
Thermal Conductivity	:	0.9W/mK
Dielectric Strength	:	42kv/mm
Specific Gravity	:	2.04
Packaging	:	2ml Syringe (bag of 10) 10ml Syringe (bag of 20) 35ml Syringe (bag of 10)

STORAGE

The product may be stored at normal ambient temperatures and has a shelf life of not less than 12 months with correct storage. Aerosols should always be stored below 50°C, away from direct heat and naked flame.

HEALTH AND SAFETY

Health and Safety sheet available separately.

MISREPRESENTATION ACT 1967

TRADE DESCRIPTIONS ACT 1968

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